

# Atomic layer deposition of superconducting films and multilayers for SRF

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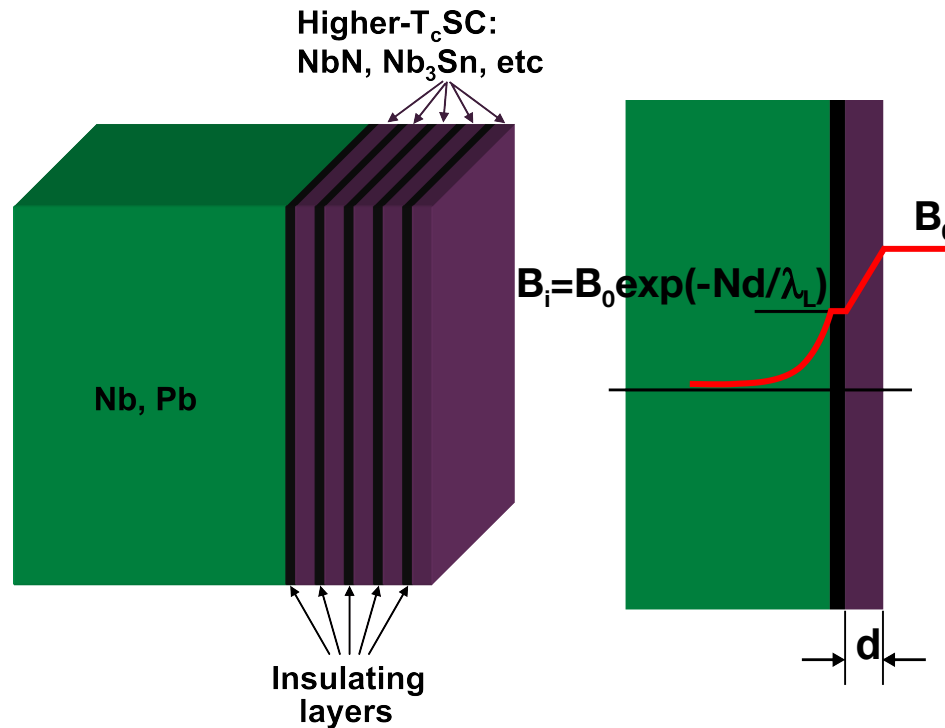
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# Multilayer thin films for SRF

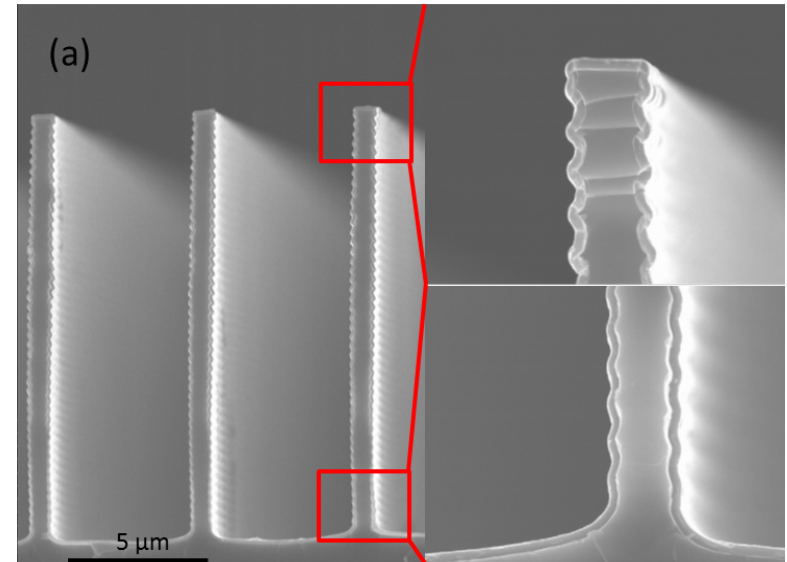
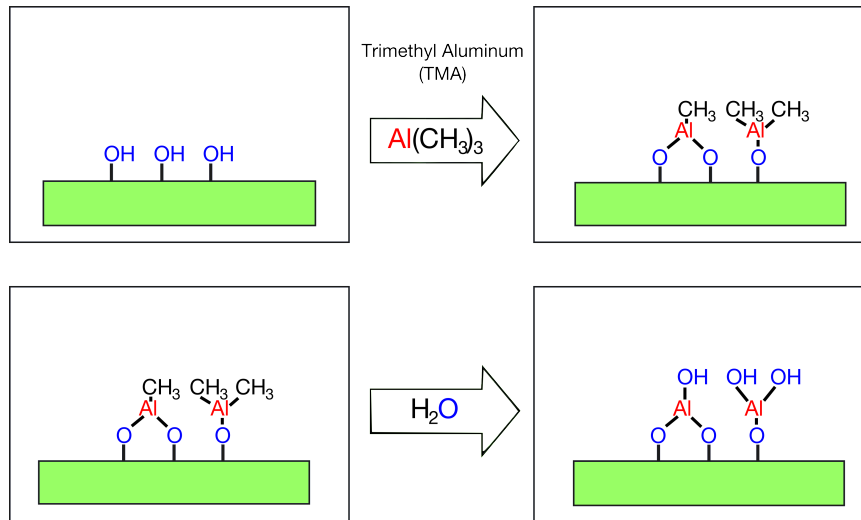
Superconductor-Insulator multilayer [Gurevich, *Appl. Phys. Lett.* **88**, 012511 (2006)]



- Potential path to high  $E_{acc}$  and high  $Q_0$

# Atomic layer deposition (ALD)

A thin film synthesis process based on sequential, self-limiting surface reactions between vapors of chemical precursors and a solid surface to deposit films in an atomic layer-by-layer manner.



## Advantages:

- Atomic-level control of thickness and composition
- Smooth, continuous, pinhole-free coatings on large area substrates
- No line-of-sight limits → excellent conformality over complex shaped surfaces

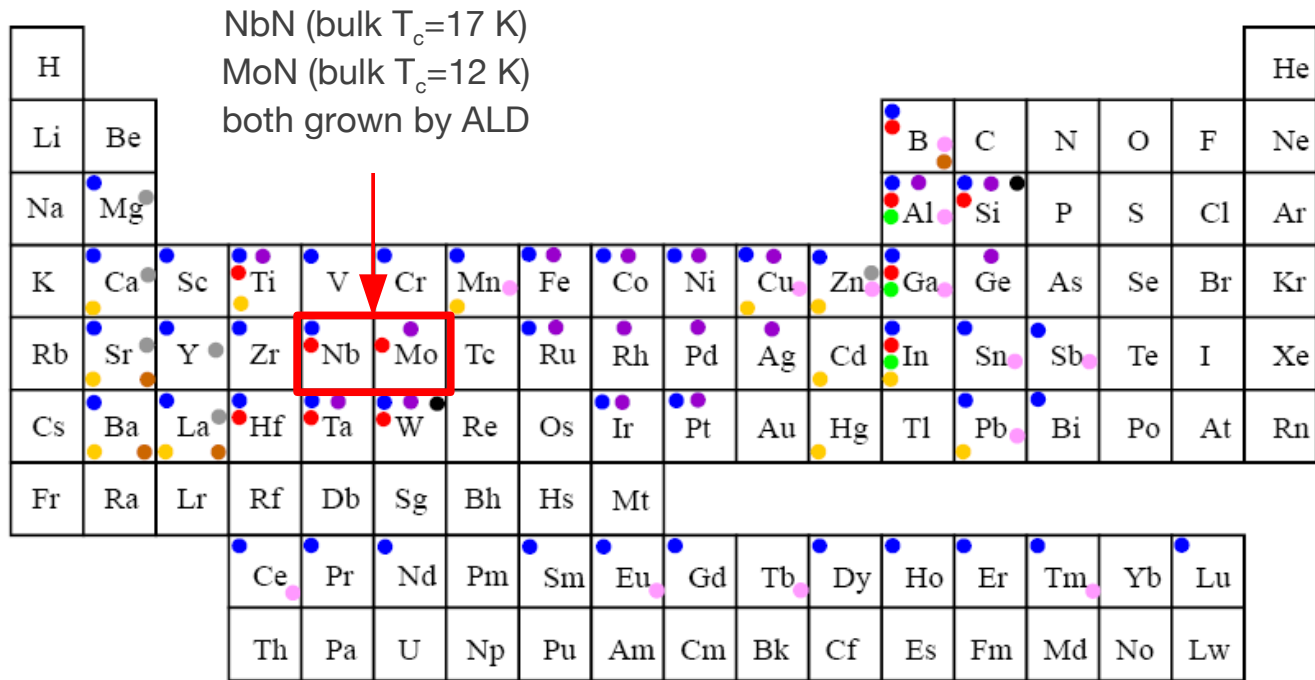
*Coat inside Nb SRF cavity with precise, layered structure → ALD*

# ALD thin film materials

H																	He	
Li	Be											B	C	N	O	F	Ne	
Na	Mg											Al	Si	P	S	Cl	Ar	
K	Ca	Sc	Ti	V	Cr	Mn	Fe	Co	Ni	Cu	Zn	Ga	Ge	As	Se	Br	Kr	
Rb	Sr	Y	Zr	Nb	Mo	Tc	Ru	Rh	Pd	Ag	Cd	In	Sn	Sb	Te	I	Xe	
Cs	Ba	La	Hf	Ta	W	Re	Os	Ir	Pt	Au	Hg	Tl	Pb	Bi	Po	At	Rn	
Fr	Ra	Lr	Rf	Db	Sg	Bh	Hs	Mt										
			Ce	Pr	Nd	Pm	Sm	Eu	Gd	Tb	Dy	Ho	Er	Tm	Yb	Lu		
			Th	Pa	U	Np	Pu	Am	Cm	Bk	Cf	Es	Fm	Md	No	Lw		

- Oxide
- Nitride
- Phosphide/Arsenide
- Sulphide/Selenide/Telluride
- Element
- Carbide
- Fluoride
- Dopant

# ALD superconductors?



- Oxide
- Nitride
- Phosphide/Arsenide
- Sulphide/Selenide/Telluride
- Element
- Carbide
- Fluoride
- Dopant

Except in one paper, superconductivity has been ignored...

- Reported  $T_c = 10$  K for NbN [Hiltunen, *et al.*, *Thin Solid Films* **166**, 149 (1988)]

# Superconductors by ALD

Goal for SRF is a material with a  $T_c$  higher than bulk Nb (9.2 K)

- Niobium Silicide: NbSi
  - $\text{NbF}_5 + \text{Si}_2\text{H}_6$
  - $\text{NbF}_5 + \text{SiH}_4$
- Niobium Carbide: NbC
  - $\text{NbF}_5 + \text{Al}(\text{CH}_3)_3$
  - $\text{NbCl}_5 + \text{Al}(\text{CH}_3)_3$
- Niobium Carbo-Nitride:  $\text{NbC}_{1-x}\text{N}_x$ 
  - $\text{Al}(\text{CH}_3)_3 + \text{NbF}_5 + \text{NH}_3$
  - $\text{Al}(\text{CH}_3)_3 + \text{NbCl}_5 + \text{NH}_3$
- Molybdenum Nitride: MoN
  - $\text{MoCl}_5 + \text{NH}_3$
  - $\text{MoCl}_5 + \text{Zn} + \text{NH}_3$
- Niobium Titanium Nitride:  $\text{Nb}_{1-x}\text{Ti}_x\text{N}$ 
  - $(\text{NbF}_5, \text{TiCl}_4) + \text{NH}_3$
  - $(\text{NbCl}_5, \text{TiCl}_4) + \text{Zn} + \text{NH}_3$
- Iron Selenide:  $\text{FeSe}_x$ 
  - $\text{FeCl}_3 + \text{Se}(\text{Et}_3\text{Si})_2$

# Superconductors by ALD

Goal for SRF is a material with a  $T_c$  higher than bulk Nb (9.2 K)

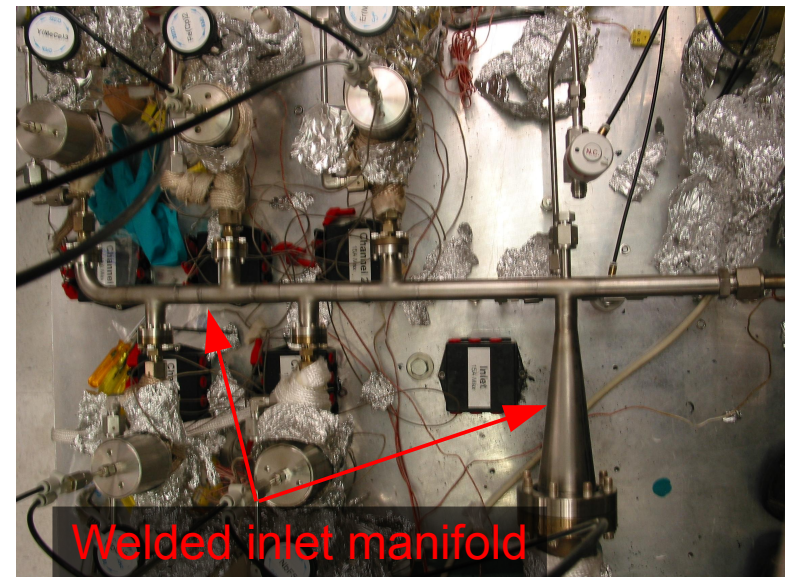
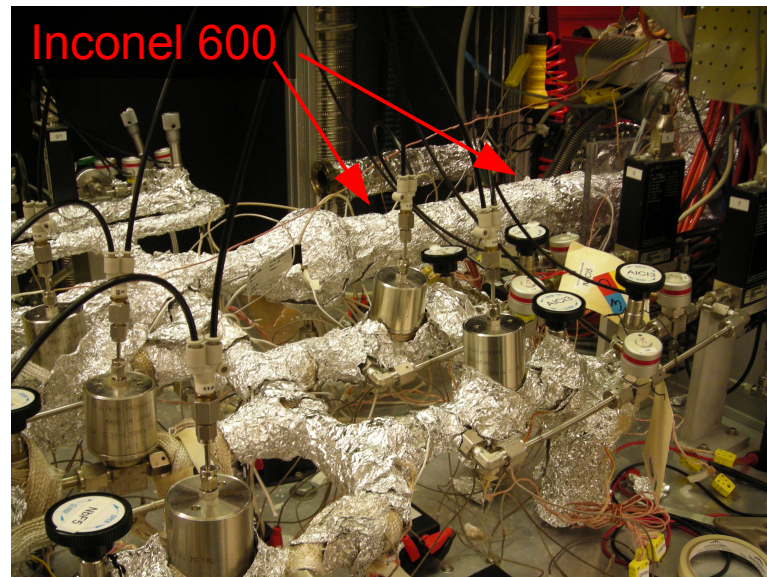
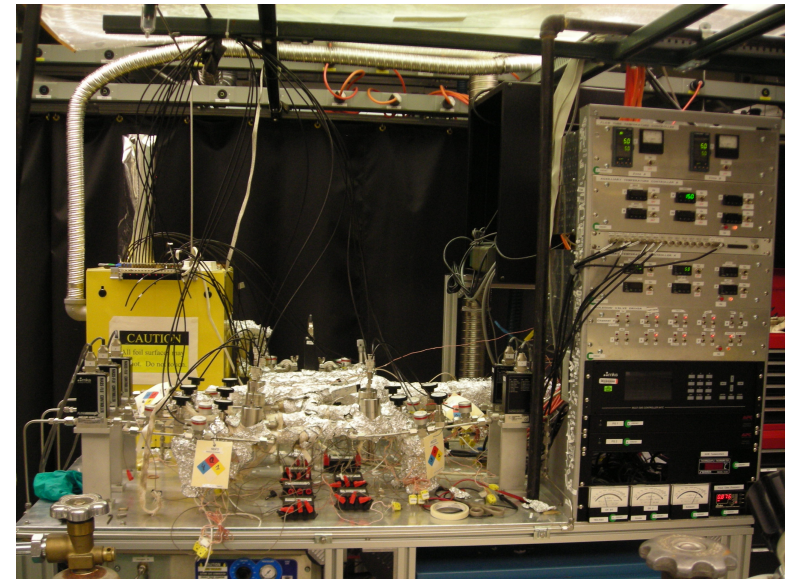
- Niobium Silicide: NbSi
  - $\text{NbF}_5 + \text{Si}_2\text{H}_6$
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- Niobium Carbide: NbC
  - $\text{NbF}_5 + \text{Al}(\text{CH}_3)_3$
  - $\text{NbCl}_5 + \text{Al}(\text{CH}_3)_3$
- Niobium Carbo-Nitride:  $\text{NbC}_{1-x}\text{N}_x$ 
  - $\text{Al}(\text{CH}_3)_3 + \text{NbF}_5 + \text{NH}_3$
  - $\text{Al}(\text{CH}_3)_3 + \text{NbCl}_5 + \text{NH}_3$
- Molybdenum Nitride: MoN
  - $\text{MoCl}_5 + \text{NH}_3$
  - $\text{MoCl}_5 + \text{Zn} + \text{NH}_3$
- Niobium Titanium Nitride:  $\text{Nb}_{1-x}\text{Ti}_x\text{N}$ 
  - $(\text{NbF}_5, \text{TiCl}_4) + \text{NH}_3$
  - $(\text{NbCl}_5, \text{TiCl}_4) + \text{Zn} + \text{NH}_3$
- Iron Selenide:  $\text{FeSe}_x$ 
  - $\text{FeCl}_3 + \text{Se}(\text{Et}_3\text{Si})_2$



# Viscous flow ALD reactor

## Key features:

- Inconel 600 reactor tube (superior corrosion resistance)
  - Halide precursors ( $\text{NbCl}_5$ ,  $\text{TiCl}_4$ , etc.)
- All-welded precursor inlet manifold (reduced sites for potential leaks)
  - Oxygen contamination in nitride films





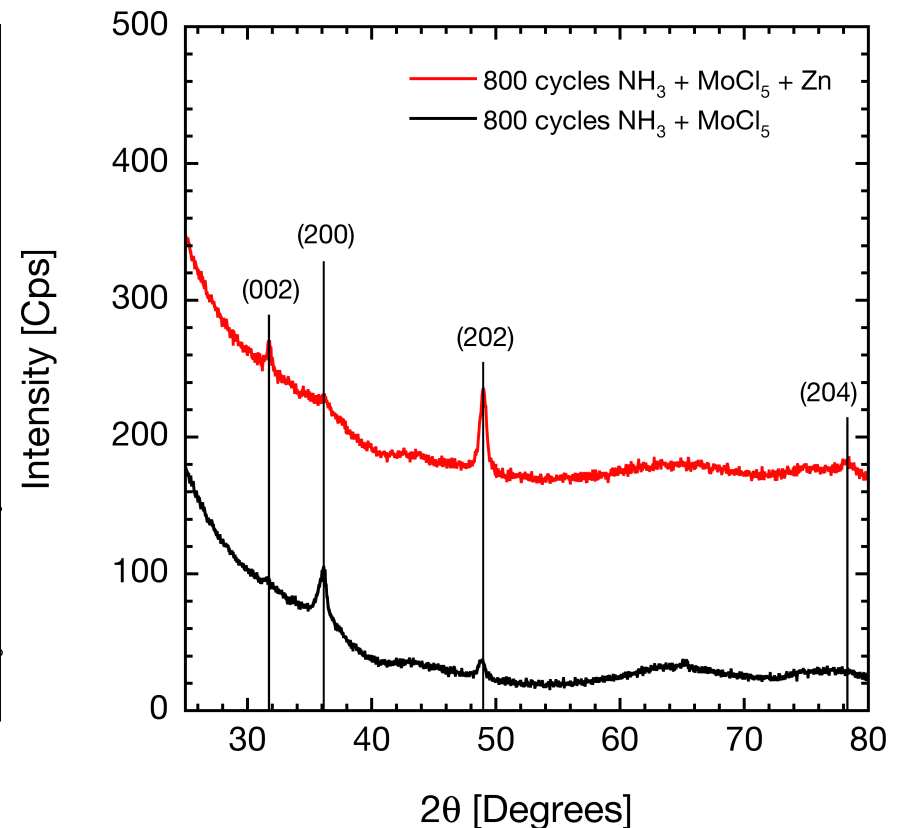
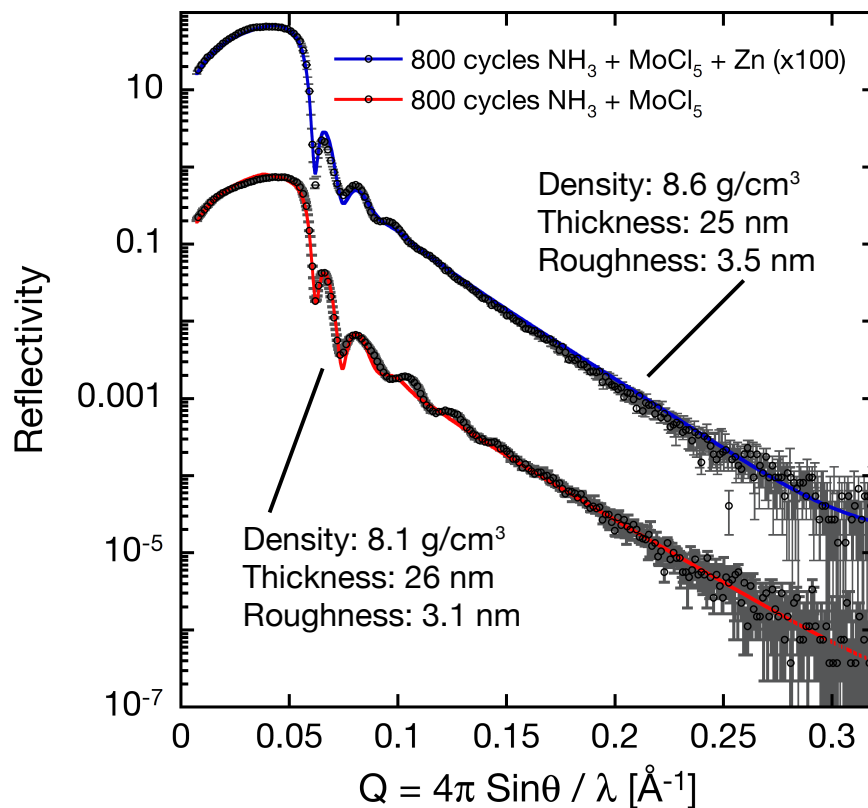
# Thin film characterization

- X-ray photoemission spectroscopy (XPS)
- X-ray reflectivity (XRR)
- X-ray diffraction (XRD)
- Synchrotron grazing-incidence x-ray diffraction (GIXRD)
- Scanning electron microscopy (SEM)
- Transmission electron microscopy (TEM)
- DC electrical transport (down to 1.6 K)
- SQUID magnetometry
  
- Atom probe tomography (APT) [Seidman, NU]
- Rutherford backscattering spectroscopy (RBS) [Evans Analytical]

# Molybdenum nitride: MoN

## Effects of intermittent Zn pulse

- Chemistry:  $\text{MoCl}_5 + \text{NH}_3$  versus  $\text{MoCl}_5 + \text{Zn} + \text{NH}_3$  at  $450^\circ\text{C}$
- Hexagonal MoN in both cases, higher density & change in texture with Zn

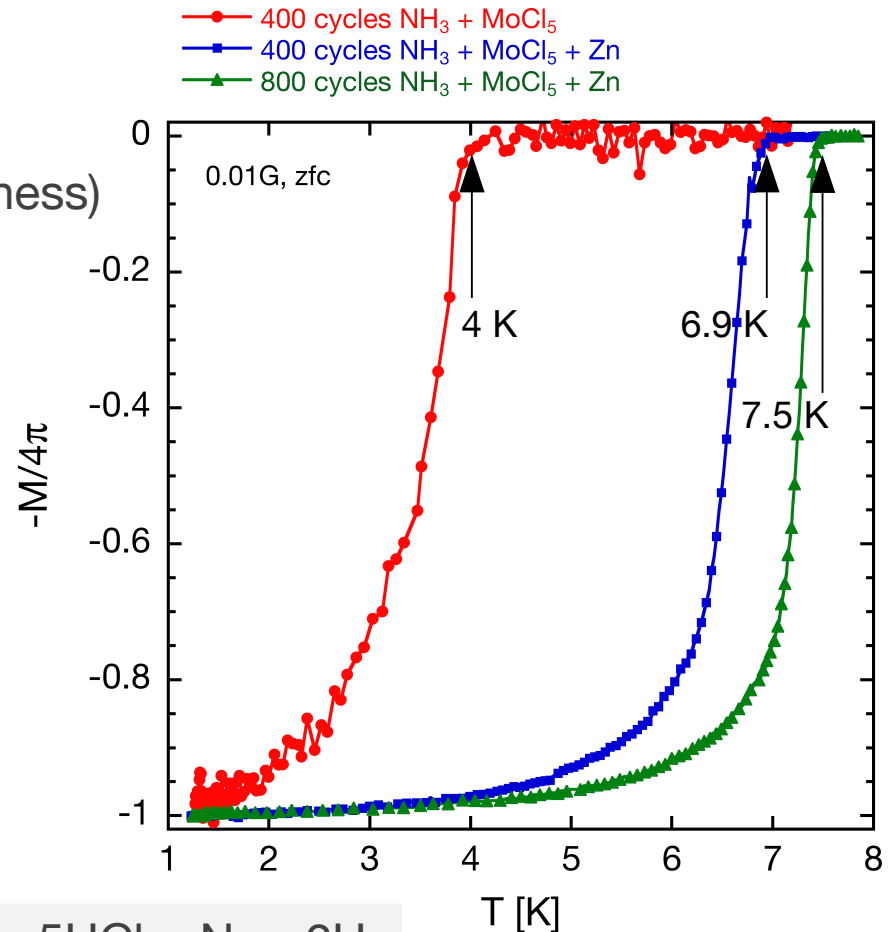
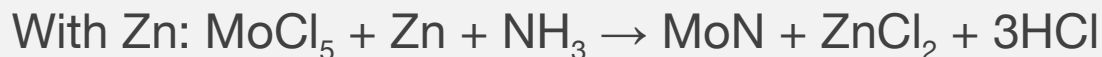
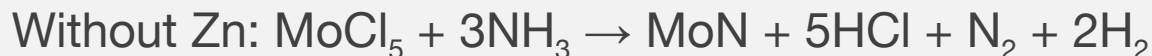


# MoN: Superconducting $T_c$ (SQUID)

## Addition of Zn leads to:

- ~2x increase in  $T_c$  (equivalent thickness)
  - Peak  $T_c = 7.5$  K for 25 nm film
- Decrease in RT resistivity
  - 200  $\mu\Omega$ -cm without Zn
  - 120  $\mu\Omega$ -cm with Zn

- No chlorine, zinc observed by XPS
- Could be related to film density
  - 88-93% of bulk (9.2 g/cm<sup>3</sup>)
- Could be due to hydrogen:



# Niobium titanium nitride: $\text{Nb}_{1-x}\text{Ti}_x\text{N}$

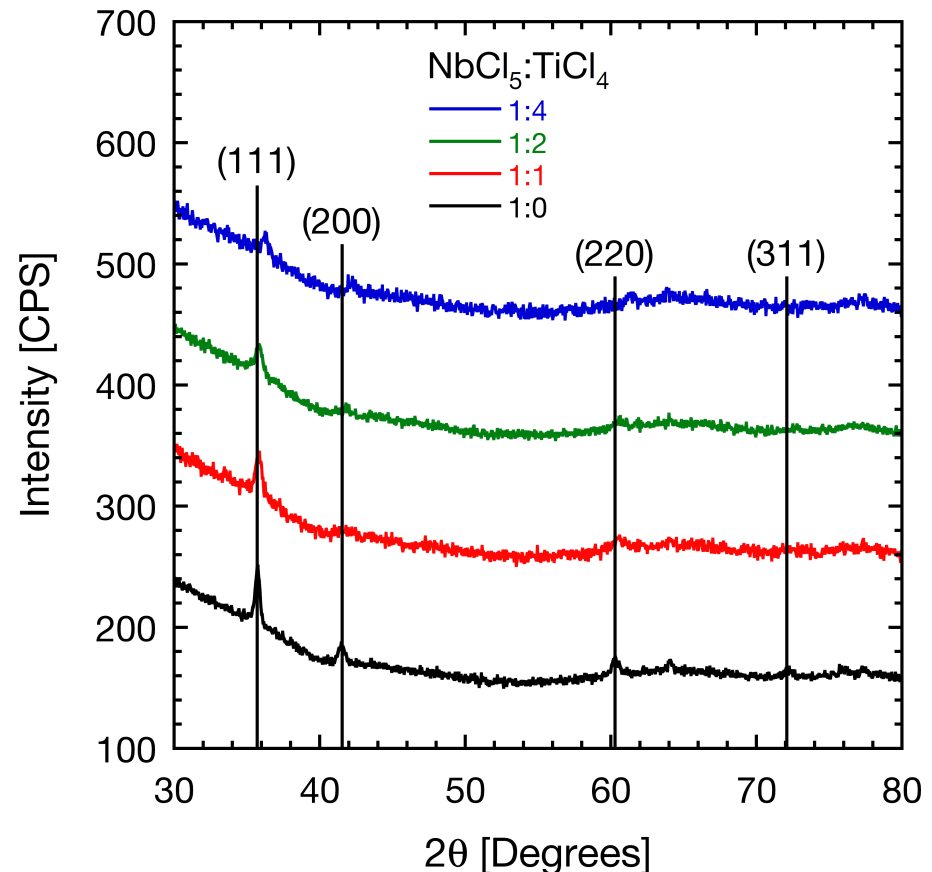
- Chemistry:  $(\text{NbCl}_5:\text{TiCl}_4) + \text{Zn} + \text{NH}_3$  at 450°C, 500°C
- Can vary Ti content with  $\text{NbCl}_5:\text{TiCl}_4$  ratio (1:2 ~ 20% TiN)
  - Cubic  $\delta$  phase in all films

With increasing TiN

- Peaks shift to higher angle
- Density decreases
  - 7.2 g/cm<sup>3</sup> (1:0)
  - 5.7 g/cm<sup>3</sup> (1:4)
- RT resistivity decreases
  - 380  $\mu\Omega\text{-cm}$  (1:0)
  - 130  $\mu\Omega\text{-cm}$  (1:4)

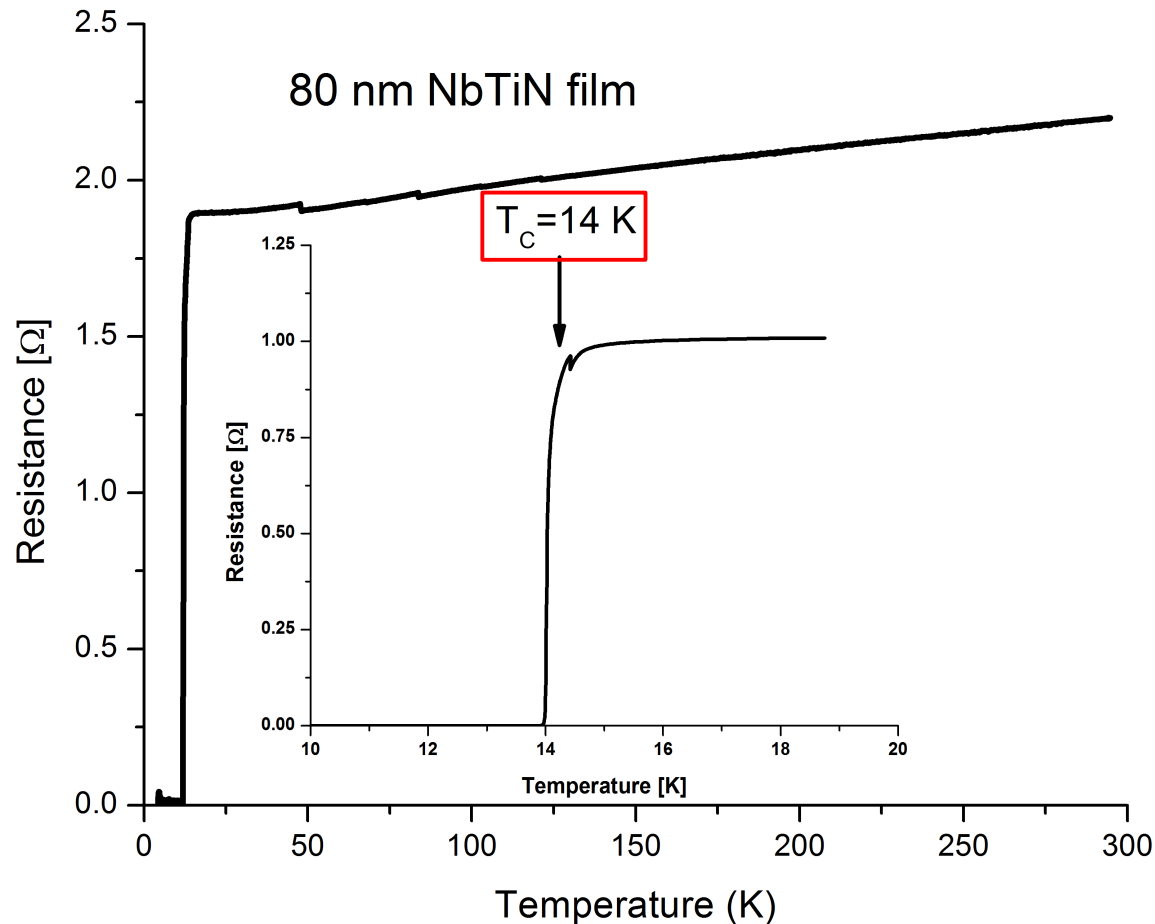
Impurity content: 0.05 atom % Cl

Are they good superconductors?



# Optimized growth of Nb<sub>1-x</sub>Ti<sub>x</sub>N

- Achieved superconducting  $T_c=14$  K, **40% higher than any other ALD film**
- Nearly 5 K higher than Nb

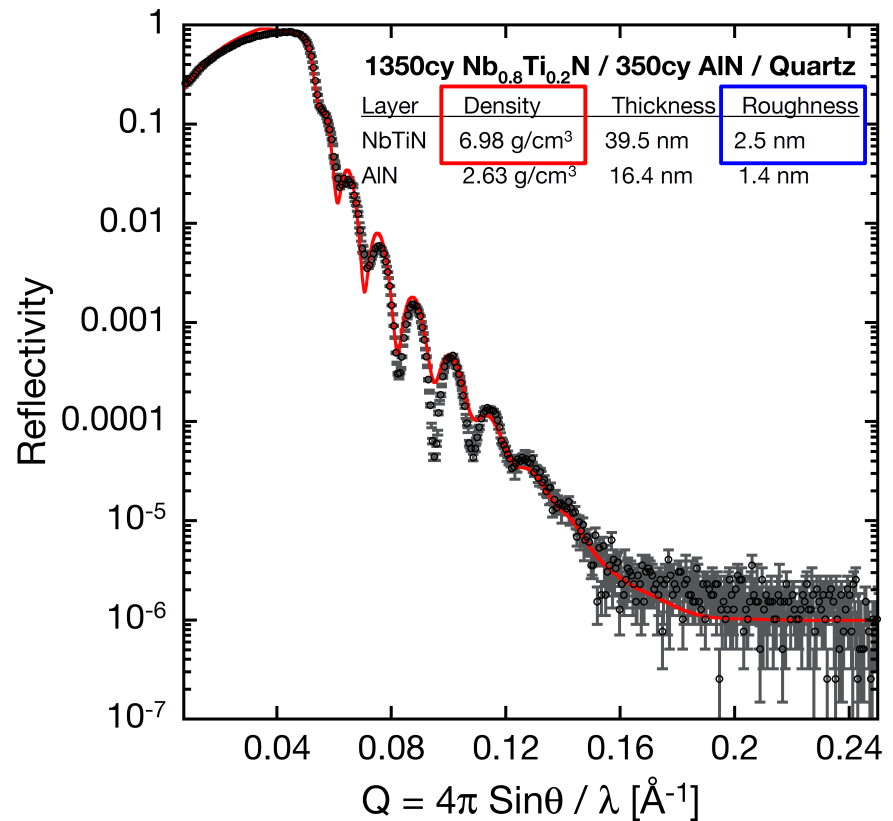
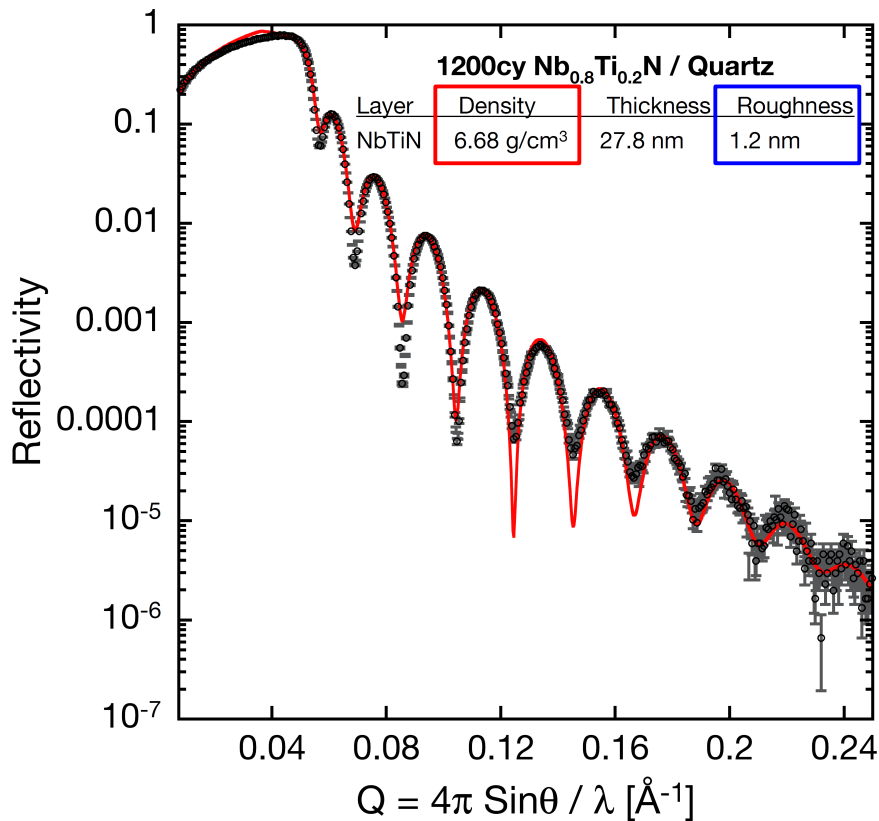


# Nb<sub>1-x</sub>Ti<sub>x</sub>N-based superconductor-insulator structures

## Aluminum nitride: AlN

- Oxygen-free insulator, stable interface with Nb(Ti)N
- Good thermal conductivity (285 W/m-K)
- Similar structure to Nb(Ti)N
  - 0.27% mismatch between in-plane spacing of (0001)-oriented AlN and (111)-oriented NbN
- Can be grown with AlCl<sub>3</sub> and NH<sub>3</sub> at same temperature as Nb(Ti)N
  - No thermal cycling between deposition steps
  - ALD previously demonstrated [K.-E. Elers, et al. *J. de Phys. IV* **5** (1995)]
- NbN/AlN multilayers grown previously by sputtering
  - Enhanced  $J_c$  at high fields [J.M. Murduck, et al. *Appl. Phys. Lett.* **62** (1988)]
  - Model system for vortex matter in HTS [E.S. Sadki, et al. *Phys. Rev. Lett.* **85** (2000)]

# Nb<sub>1-x</sub>Ti<sub>x</sub>N / AlN: X-ray reflectivity



- Density ~5% higher with AlN
- Roughness ~2x higher with AlN
- Change in thickness/cycles (difference in nucleation delay)

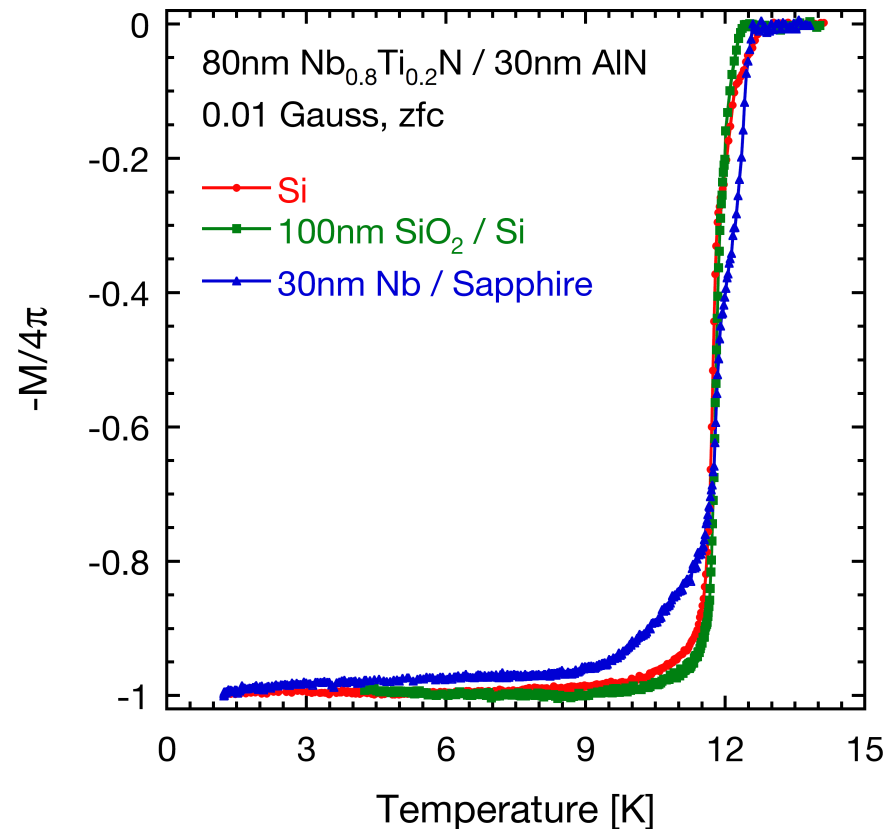
# Nb<sub>1-x</sub>Ti<sub>x</sub>N / AlN multilayers

- 40 nm Nb<sub>0.8</sub>Ti<sub>0.2</sub>N / 15 nm AlN (single bilayer and 2x stack)
- 80 nm Nb<sub>0.8</sub>Ti<sub>0.2</sub>N / 30 nm AlN (single bilayer and 2x stack)
  - Quartz, Si(001), 100 nm SiO<sub>2</sub>/Si(001), 30 nm Nb/Sapphire, and cavity-grade Nb



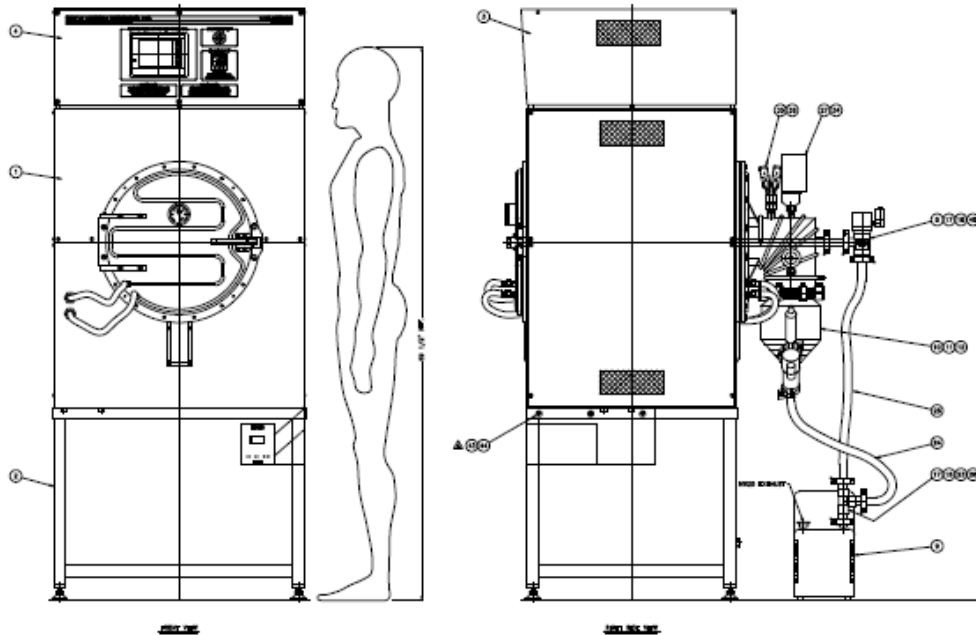
**Optimized Nb<sub>1-x</sub>Ti<sub>x</sub>N/AlN ALD growth process ( $T_c = 14$  K) is now ready for coating Nb SRF cavities**

- Will enable testing the effects of S-I multilayer on cavity performance



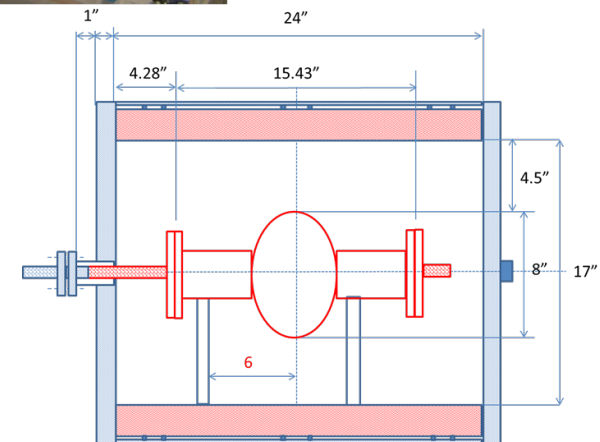


# Scaling ALD to coat cavities



## New ALD system currently being assembled

- Clean room 100 environment
- Up to 650°C in UHV ( $10e-8$  Torr)
- *In situ* processing
- Accommodate single-cell ILC cavities



# Fe-based superconductors: Initial studies of $\text{FeSe}_x$

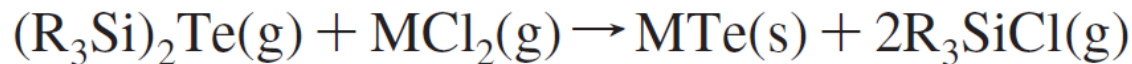
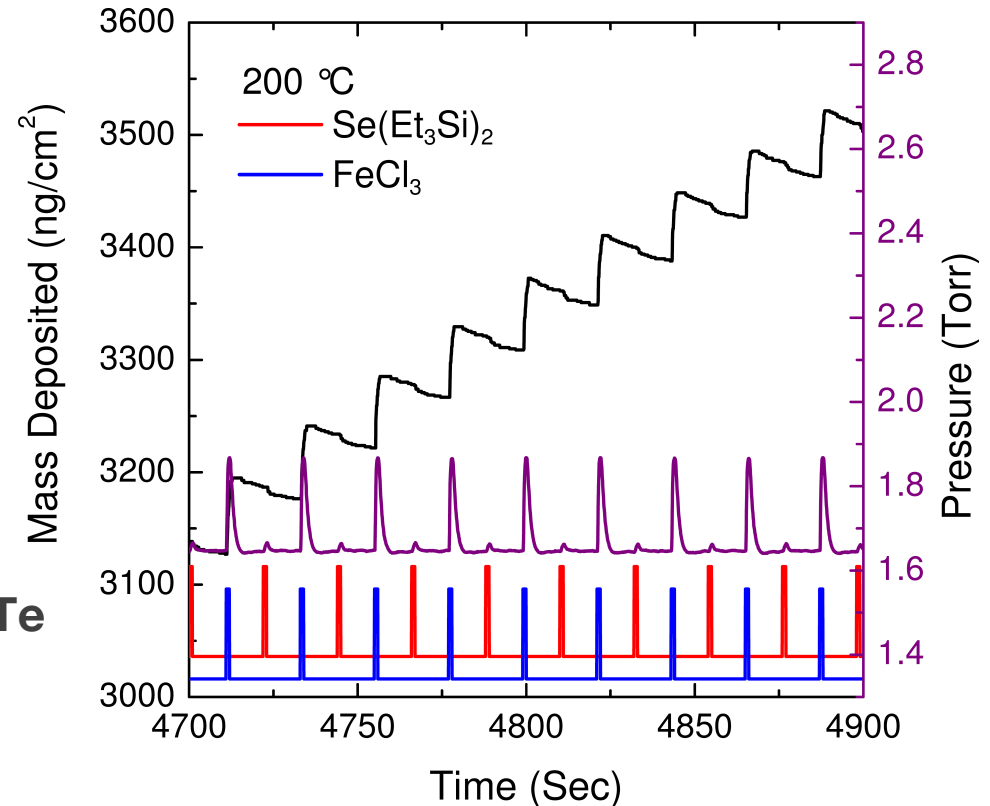
## Promising new Fe-based superconductors ( $\text{FeSe}_{1-x}\text{Te}_x$ )

- $T_c$  reported up to 37 K
- Remain superconducting in high magnetic fields (>45 T)

## New custom precursors for Se, Te

(J. Schlueter, S. Sullivan ANL)

- $(\text{Et}_3\text{Si})_2\text{Te} / (\text{Et}_3\text{Si})_2\text{Se}$
- $(^t\text{BuMe}_2\text{Si})_2\text{Te} / (^t\text{BuMe}_2\text{Si})_2\text{Se}$



# Summary

- Growth of single-phase hexagonal-MoN at 450°C
- Demonstrated ~2x increase in  $T_c$  in MoN with intermittent Zn dose (MoCl<sub>5</sub> + Zn + NH<sub>3</sub>)
- Optimized growth of Nb<sub>1-x</sub>Ti<sub>x</sub>N to achieve superconducting  $T_c = 14$  K, 40% higher than any other ALD film and ~5 K higher than Nb
- Demonstrated successful ALD growth of Nb<sub>1-x</sub>Ti<sub>x</sub>N/AlN S-I multilayers on flat substrates (Si, SiO<sub>2</sub>, Sapphire, Nb)
- Assembly of new UHV ALD system for coating 1-cell ILC cavities
- New precursors for Fe-based superconductors (FeSe<sub>1-x</sub>Te<sub>x</sub>)
- Plasma-enhanced ALD system now online and in use

# Thank you for your attention